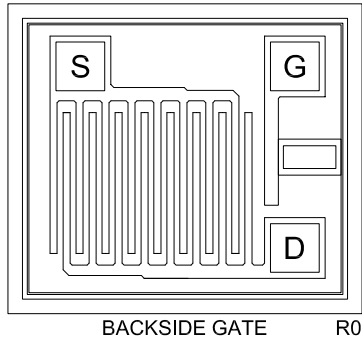


The CP613V-J175 is a silicon P-Channel JFET designed for switching applications.



MECHANICAL SPECIFICATIONS:

Die Size	24 x 21 MILS
Die Thickness	7.1 MILS
Source Bonding Pad Size	3.3 x 3.3 MILS
Drain Bonding Pad Size	3.3 x 3.3 MILS
Gate Bonding Pad Size	3.3 x 3.3 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au-As – 10,000Å
Scribe Alley Width	1.97 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	27,725

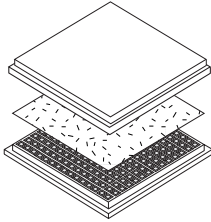
MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

	SYMBOL		UNITS
Gate-Drain Voltage	V_{GD}	30	V
Gate-Source Voltage	V_{GS}	30	V
Gate Current	I_G	50	mA
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{GSS}	$V_{GS}=20\text{V}$			1.0	nA
I_{DSS}	$V_{DS}=15\text{V}$	7.0		60	mA
BV_{GSS}	$I_G=1.0\mu\text{A}$	30			V
$V_{GS(OFF)}$	$V_{DS}=15\text{V}, I_D=10\text{nA}$	3.0		6.0	V
$r_{DS(ON)}$	$V_{DS}=0.1\text{V}$			125	Ω

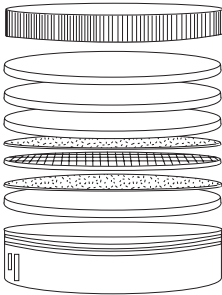
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

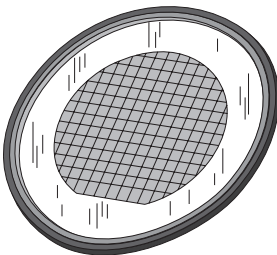
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

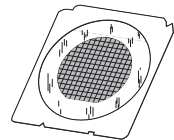
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

Worldwide Distributors:
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